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APPLICATION NO.	F	ILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/006,704		12/10/2001	Shane J. Trapp	M4065.0369/P369-A	M4065.0369/P369-A 3229	
24998	7590	05/31/2005		EXAMINER		
		IRO MORIN &	UMEZ ERONIN	UMEZ ERONINI, LYNETTE T		
2101 L Stree	,			ADTIBUT	DADED MEDIDED	
Washington, DC 20037				ART UNIT	PAPER NUMBER	
				1765		

DATE MAILED: 05/31/2005

Please find below and/or attached an Office communication concerning this application or proceeding.

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	Application No.	Applicant(s)				
	10/006,704	TRAPP, SHANE				
Office Action Summary	Examiner	Art Unit				
	Lynette T. Umez-Eronini	1765				
The MAILING DATE of this communication app Period for Reply	pears on the cover sheet with the c	orrespondence address				
A SHORTENED STATUTORY PERIOD FOR REPL THE MAILING DATE OF THIS COMMUNICATION. - Extensions of time may be available under the provisions of 37 CFR 1.1 after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, a repl If NO period for reply is specified above, the maximum statutory period Failure to reply within the set or extended period for reply will, by statute Any reply received by the Office later than three months after the mailin earned patent term adjustment. See 37 CFR 1.704(b).	136(a). In no event, however, may a reply be tin by within the statutory minimum of thirty (30) day will apply and will expire SIX (6) MONTHS from a, cause the application to become ABANDONE	nely filed s will be considered timely. the mailing date of this communication. D (35 U.S.C. § 133).				
Status						
1)⊠ Responsive to communication(s) filed on 21 A	nril 2005	•				
<u> </u>	s action is non-final.					
3) Since this application is in condition for allowa		secution as to the merits is				
	closed in accordance with the practice under <i>Ex parte Quayle</i> , 1935 C.D. 11, 453 O.G. 213.					
Disposition of Claims						
4) ☐ Claim(s) 26-32,71 and 77 is/are pending in the 4a) Of the above claim(s) is/are withdray 5) ☐ Claim(s) is/are allowed. '6) ☐ Claim(s) 26-32,71 and 77 is/are rejected. 7) ☐ Claim(s) is/are objected to. 8) ☐ Claim(s) are subject to restriction and/or	wn from consideration.					
Application Papers						
9)☐ The specification is objected to by the Examine 10)☑ The drawing(s) filed on 10 December 2001 is/a Applicant may not request that any objection to the Replacement drawing sheet(s) including the correct 11)☐ The oath or declaration is objected to by the Example 11.	are: a) \square accepted or b) \square object drawing(s) be held in abeyance. See tion is required if the drawing(s) is obj	e 37 CFR 1.85(a). ected to. See 37 CFR 1.121(d).				
Priority under 35 U.S.C. § 119						
12) Acknowledgment is made of a claim for foreign a) All b) Some * c) None of: 1. Certified copies of the priority document 2. Certified copies of the priority document 3. Copies of the certified copies of the priority document application from the International Bureau * See the attached detailed Office action for a list	s have been received. s have been received in Application rity documents have been receive u (PCT Rule 17.2(a)).	on No ed in this National Stage				
Attachment(s)						
Notice of References Cited (PTO-892)	4) 🔲 Interview Summary	(PTO-413)				
P) Notice of Draftsperson's Patent Drawing Review (PTO-948) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08) Paper No(s)/Mail Date	Paper No(s)/Mail Da					

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DETAILED ACTION

Request for Continued Examination

1. A request for continued examination under 37 CFR 1.114, including the fee set forth in 37 CFR 1.17(e), was filed in this application after final rejection. Since this application is eligible for continued examination under 37 CFR 1.114, and the fee set forth in 37 CFR 1.17(e) has been timely paid, the finality of the previous Office action has been withdrawn pursuant to 37 CFR 1.114. Applicant's submission filed on 4/21/2005 has been entered.

The previous rejection has been withdrawn because:

In (Currently amended) claims 26 and 77, "A composition . . . wherein said at least one fluorocarbon and ammonia form a reactive mixture;" and

In (Currently amended) claim 71"A composition . . . at least one other fluorocarbon, and NH₃, wherein said CF₄, at least one other fluorocarbon, and NH₃ form a reactive mixture" raise new issues that would require further consideration.

Rejections - 35 USC § 102

2. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

3. Claims 26-30, and 32 are rejected under 35 U.S.C. 102(b) as being anticipated by Hamrah et al. (EP 0 553961 A2).

Hamrah teaches a reactive ion etch process for etching oxide (insulative) layers by using a standard oxide etch chemistry that includes CHF₃, Ar, and CF₄ (page 2, lines 1-5, 16-18), adding a gaseous source of hydrogen radical, such as ammonia to the oxide RIE etching chemistries (page 2, lines 32-34), and supplying a selected reactive gas mixture including a gaseous source of hydrogen radicals and RF are supplied to the chamber to establish an etching plasma (page 2, lines 44-46). The aforementioned reads on,

A composition suitable for use in etching an insulative layer formed over a substrate in a semiconductor device, said composition comprising:

a flowing plasma etchant mixture consisting essentially of at least one fluorocarbon and ammonia. Since Hamrah disclose the same composition as claimed by applicants, then using Hamrah's composition in the same manner as claimed by applicants would inherently result wherein said at least one fluorocarbon and ammonia form a reactive mixture, as recited in claim 26.

The above aforementioned further reads on,

wherein said fluorocarbon is at least one member selected from the group consisting of fluorocarbons, as in claim 27;

wherein said fluorocarbon is at least one member selected from the group consisting of C_4F_8 , C_4F_6 , C_5F_8 , CF_4 , C_2F_6 , CHF_3 , and CH_2F_2 , in claim 28; and

wherein said fluorocarbon is at least one member selected from the group consisting of CF₄, CHF₃, and CH₂F₂, in claim 29;

wherein said fluorocarbon is at least two members selected from the group consisting of and is a combination of CF₄, CHF₃ and CH₂F₂, in claim 30; and

Since Hamrah uses the same etchants to etch an insulation layer as that of the claimed invention then, using Hamrah's etchants in the same manner as in the claimed invention would result wherein said composition is ineffective to remove side wall spacers of a gate formed over said substrate, in claim 32.

The above aforementioned also reads on,

A composition suitable for use in etching an insulative layer formed over a substrate in a semiconductor device, said composition consisting of:

a flowing plasma etchant mixture consisting of CF₄, at least one other fluorocarbon, and NH₃. Since Hamrah discloses the same composition as claimed by applicants, then using Hamrah's composition in the same manner as claimed by applicants would result wherein said CF₄, at least one other fluorocarbon and NH₃, form a reactive mixture, as recited in claim 71.

The said aforementioned further reads on,

A composition suitable for use in etching an insulative layer formed over a substrate in a semiconductor device, said composition consisting of: a gaseous etchant mixture, consisting of at least one fluorocarbon and ammonia. Since Hamrah discloses the same composition as claimed by applicants, then using Hamrah's composition in the

same manner as claimed by applicants would result wherein said at least one fluorocarbon and ammonia NH₃, form a reactive mixture, as recited in claim 72.

Claim Rejections - 35 USC § 103

- 4. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
 - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 5. This application currently names joint inventors. In considering patentability of the claims under 35 U.S.C. 103(a), the examiner presumes that the subject matter of the various claims was commonly owned at the time any inventions covered therein were made absent any evidence to the contrary. Applicant is advised of the obligation under 37 CFR 1.56 to point out the inventor and invention dates of each claim that was not commonly owned at the time a later invention was made in order for the examiner to consider the applicability of 35 U.S.C. 103(c) and potential 35 U.S.C. 102(e), (f) or (g) prior art under 35 U.S.C. 103(a).
- 6. Claim 31 is rejected under 35 U.S.C. 103(a) as being unpatentable over Hamrah (EP '961 A2) as applied to claim 26 above, and further in view of Becker et al. (US 6,015,760).

Hamrah differs only in failing to teach wherein said fluorocarbon is a combination of CF₄, CHF₃ and CH₂F₂, in claim 31.

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Becker teaches anisotropic etching takes place primarily in the vertical direction

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so that feature widths substantially match the photoresist pattern widths (column 1, lines

40-43); and anisotropic etching is utilized when feature sizing after etching must be

maintained within specific limits so as not to violate alignment tolerances or design rules

(column 1, line 43-46); and selectively etching SiO₂ layer with respect to a nitride layer

by using a fluorinated chemical etchant system that comprises: CF₄, CHF₃ and a CH₂F₂

additive material (column 4, lines 16-18) and in this way, the etching process provides

for the formation of sidewalls in etched layers which have a substantially vertical profile

(column 4, lines 29-31).

It is the examiner's position that it would have been obvious to one having

ordinary skill in the art at the time of the claim invention to modify Hamrah by combining

the etchants as taught by Becker for the purpose of meeting specific limits that would

not violate alignment tolerances or design rules (Becker, column 1, lines 43-46).

Any inquiry concerning this communication or earlier communications from the

examiner should be directed to Lynette T. Umez-Eronini at 571-272-1470. The

examiner is normally unavailable on the First Friday.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's

supervisor, Nadine Norton can be reached on 571-272-1465. The fax phone number

for the organization where this application or proceeding is assigned is 703-872-9306.

Itue

NADINE G. NORTON SUPERVISORY PATENT EXAMINER

May 16, 2005